Amendments to the Specification:

Please replace paragraphs [0018], [0019] and [0020] with the following amended paragraphs:

[0018] In Fig. 4(e), a film of a cladding layer 6' is formed to cover the core block 5'. In Fig. 4(f), an L-shaped core block is formed by removing a core resin of a part interposed between the core of a horizontal portion and the core of a vertical portion, which constitute an L-shape, by techniques of photolithography and Reactive Ion Etching. In Fig. 4(g), the entire surface is filled with a cladding layer 8', then the core resin and the cladding resin of unnecessary portions between channels and between devices are removed to form L-shaped cores 7' (7b'), then void spaces between channels and between devices are covered with cladding layers, and then the surface is subjected to a flattening treatment. Fig. **[[2]]** 5(B) shows a perspective view of the multichannel cores 7' during this step. In Fig. 4(h), a second temporary substrate 9' is attached by an adhesive 10', the sacrifice layer 2' is removed by using an acid or the like, and the first temporary substrate 1' is removed. In Fig. 4(i), a V-groove is formed by a dicing saw, and a reflecting mirror 12' is formed at a corner portion by using a technique such as magnetron sputtering to form a mirror. As the reflecting mirror, there is used a metal film, a dielectric multilayer film or the like. To form the mirror surface, there is also preferable a method in which a prism having a reflecting film formed thereon is disposed in the V-groove and then it is fixed by adhesive or the like. Furthermore, it is also possible to make a cut of 45 degrees with a dicing saw, then insert a film having a reflecting film formed thereon thereinto, and then fix that with adhesive.

[0019] In Fig. 4(j), the V-groove is filled with a cladding resin 13' to make the device surface flat. In Fig. 4(k), a substrate 14' is attached to the waveguide. As the substrate, it is possible to use a glass substrate, silicon substrate, resin substrate or the like. In Fig. 4(l), ~~the sacrifice layer 2' is removed by acid or the like, then~~ the second temporary substrate 9' is removed, and then it is cut and

separated into a multichannel optical path changing device by a dicing saw, thereby producing a multichannel optical path changing device.

[0020] Fig. 7 is a view showing a second example of the method (second method) for producing a multichannel optical path chancing device according to the present invention.

Fig. 7(a) shows one prepared by forming a film of a sacrifice layer 2' on a first temporary substrate 1' and then forming thereon a cladding layer 3' and a core layer 4'. In Fig. 7(b), a core resin of a part interposed between the core of a horizontal portion and the core of a vertical portion, which constitute an L-shape, is removed by conducing a selective etching by techniques of photolithography and Reactive Ion Etching, thereby forming an L-shaped core block. In Fig. 7(c), the removed portion is filled with a cladding resin. In Fig. 7(d), between waveguides and other core resin unnecessary portions are selectively removed to form L-shaped cores. Then, in Fig. 7(e), the removed portion is filled with a cladding resin, thereby simultaneously forming L-shaped cores under a condition that their respective positional relationships are maintained. Fig. 8 shows a perspective view upon this. After that, a multichannel optical path changing device is produced by a method similar to that of Fig. 4(h) to Fig. 4(l) in the first example.